Power line chokes

Ring core chokes with iron powder core
250 V AC, 0.3 … 3 A, 0.033 … 1.2 mH, +60 °C

Series/Type: B82623
Date: July 2012
Power line chokes

Ring core chokes with iron powder core

Rated voltage 250 V AC/350 V DC
Rated current 0.3 ... 3 A
Rated inductance 0.033 ... 1.2 mH

Construction
■ Ring core double choke
■ Iron powder core with epoxy coating
■ Polycarbonate case (UL 94 V-0)
■ Polyurethane potting (UL 94 V-0)
■ Sector winding

Features
■ Effective suppression of differential-mode interferences at higher frequencies
■ Moderate inductance decrease at current load
■ Suitable for wave soldering
■ Design complies with EN 60938-2 (VDE 0565-2) and UL 1283
■ UL and ENEC (VDE) approvals
■ RoHS-compatible

Applications
■ Suppression of differential-mode interferences
■ Compact switch-mode applications
■ Reduction of harmonics and PFC

Terminals
■ Base material CuNi18Zn20
■ Layer composition Ni, Sn
■ Hot-dipped
■ Pins 0.7 × 0.7 (mm)
■ Lead spacing 15 × 25 (mm)

Marking
Manufacturer, approval signs and VDE standard number, ordering code, rated current, rated inductance, rated voltage, “GKC”, graphic symbol, date of manufacture (YYWWD.internal ID code)

Delivery mode
Blister tray in cardboard box
Power line chokes
Ring core chokes with iron powder core

Dimensional drawing and pin configuration

Tolerances to ISO 2768-C unless otherwise noted. Dimensions in mm.

Technical data and measuring conditions

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Rated voltage $V_R$</td>
<td>250 V AC (50/60 Hz) / 350 V DC</td>
</tr>
<tr>
<td>Test voltage $V_{test}$</td>
<td>1500 V AC, 2 s (winding/winding)</td>
</tr>
<tr>
<td>Rated temperature $T_R$</td>
<td>+60 °C</td>
</tr>
<tr>
<td>Rated current $I_R$</td>
<td>Referred to 50 Hz and rated temperature</td>
</tr>
<tr>
<td>Rated inductance $L_R$</td>
<td>Defined at zero DC current bias</td>
</tr>
<tr>
<td></td>
<td>Measured with Agilent 4284A at 0.1 mA, +20 °C</td>
</tr>
<tr>
<td></td>
<td>Measuring frequency: $L_R \leq 1 \text{ mH} = 100 \text{ kHz}$</td>
</tr>
<tr>
<td></td>
<td>$L_R &gt; 1 \text{ mH} = 10 \text{ kHz}$</td>
</tr>
<tr>
<td>Inductance tolerance</td>
<td>±20% at +20 °C</td>
</tr>
<tr>
<td>Inductance at rated current</td>
<td>Measured at DC magnetic bias with $I_R$ with Agilent 4284A at 0.1 mA, +20 °C, typical values</td>
</tr>
<tr>
<td></td>
<td>Measuring frequency: $L_R \leq 1 \text{ mH} = 100 \text{ kHz}$</td>
</tr>
<tr>
<td></td>
<td>$L_R &gt; 1 \text{ mH} = 10 \text{ kHz}$</td>
</tr>
<tr>
<td>DC resistance $R_{typ}$</td>
<td>Measured at +20 °C, typical values, specified per winding</td>
</tr>
<tr>
<td>Solderability (lead-free)</td>
<td>Sn96.5Ag3.0Cu0.5: +(245 ±5) °C, (3 ±0.3) s</td>
</tr>
<tr>
<td></td>
<td>Wetting of soldering area ≥ 95%</td>
</tr>
<tr>
<td></td>
<td>(to IEC 60068-2-20, test Ta)</td>
</tr>
<tr>
<td>Resistance to soldering heat</td>
<td>+(260 ±5) °C, (10 ±1) s</td>
</tr>
<tr>
<td>(wave soldering)</td>
<td>(to IEC 60068-2-20, test Tb)</td>
</tr>
<tr>
<td>Climatic category</td>
<td>40/125/56 (to IEC 60068-1)</td>
</tr>
<tr>
<td>Storage conditions (packaged)</td>
<td>−25 °C … +40 °C, ≤ 75% RH</td>
</tr>
<tr>
<td>Weight</td>
<td>Approx. 20 g</td>
</tr>
<tr>
<td>Approvals</td>
<td>EN 60938-2, UL 1283</td>
</tr>
</tbody>
</table>

Please read Cautions and warnings and Important notes at the end of this document.
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### Characteristics and ordering codes

<table>
<thead>
<tr>
<th>I&lt;sub&gt;r&lt;/sub&gt; A</th>
<th>L&lt;sub&gt;r&lt;/sub&gt; mH</th>
<th>L at I&lt;sub&gt;r&lt;/sub&gt;, typ. mH</th>
<th>R&lt;sub&gt;typ&lt;/sub&gt; Ω</th>
<th>Ordering code</th>
<th>Approvals</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.3</td>
<td>1.2</td>
<td>1.05</td>
<td>1.9</td>
<td>B82623G0001A003</td>
<td>×</td>
</tr>
<tr>
<td>0.5</td>
<td>1.0</td>
<td>0.75</td>
<td>1.1</td>
<td>B82623G0001A005</td>
<td>×</td>
</tr>
<tr>
<td>1</td>
<td>0.33</td>
<td>0.25</td>
<td>0.4</td>
<td>B82623G0001A008</td>
<td>×</td>
</tr>
<tr>
<td>2</td>
<td>0.082</td>
<td>0.062</td>
<td>0.1</td>
<td>B82623G0001A010</td>
<td>×</td>
</tr>
<tr>
<td>3</td>
<td>0.033</td>
<td>0.025</td>
<td>0.045</td>
<td>B82623G0001A011</td>
<td>×</td>
</tr>
</tbody>
</table>

× = approval granted
Impedance |Z| versus frequency f
(differential-mode) measured with windings
in series at +20 °C, typical values

|Z| \( \Omega \)
\[
\begin{array}{c|c|c|c|c|c}
\hline
f & 10^4 & 10^5 & 10^6 & 10^7 & 10^8 \\
\hline
B82623 & & & & & \\
G0001A003 & & & & & \\
G0001A005 & & & & & \\
G0001A008 & & & & & \\
G0001A010 & & & & & \\
G0001A011 & & & & & \\
\hline
\end{array}
\]

Relative inductance \( \frac{L_{op}}{L_R} \)
versus relative current \( \frac{I_{op}}{I_R} \)
measured at +20 °C, typical values

\( \frac{L_{op}}{L_R} \) \%
\[
\begin{array}{c|c|c|c|c|c}
\hline
\frac{I_{op}}{I_R} & 0.2 & 0.4 & 0.6 & 0.8 & 1 \\
\hline
B82623 & & & & & \\
G0001A003 & & & & & \\
G0001A005 & & & & & \\
G0001A008 & & & & & \\
G0001A010 & & & & & \\
G0001A011 & & & & & \\
\hline
\end{array}
\]

Current derating \( \frac{I_{op}}{I_R} \)
versus ambient temperature \( T_A \)

<table>
<thead>
<tr>
<th>( \frac{I_{op}}{I_R} )</th>
<th>0</th>
<th>0.2</th>
<th>0.4</th>
<th>0.6</th>
<th>0.8</th>
<th>1.0</th>
</tr>
</thead>
<tbody>
<tr>
<td>( T_A )</td>
<td>0</td>
<td>20</td>
<td>40</td>
<td>60</td>
<td>80</td>
<td>100</td>
</tr>
</tbody>
</table>

\( T_R = +60 °C \)
Cautions and warnings

Current-compensated ring core double chokes

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there. Derating must be applied in case the ambient temperature in the application exceeds the rated temperature of the component.
  - Ensure the operation temperature (which is the sum of the ambient temperature and the temperature rise caused by losses / self-heating) of the component in the application does not exceed the maximum value specified in the climatic category.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.

- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
  Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.

- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.

- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.
The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.

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3. The warnings, cautions and product-specific notes must be observed.

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